

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

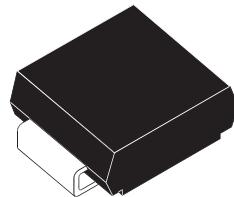
$I_{F(AV)}$	3 A
$V_{RRM}$	40 V
$T_j(\text{max})$	150°C
$V_F(\text{max})$	0.44 V

### FEATURES AND BENEFITS

- Negligible switching losses
- Low thermal resistance
- Low forward voltage drop

### DESCRIPTION

Schottky rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters. Packaged in SMC, this device is intended for use in DC/DC chargers.



**SMC**  
(JEDEC DO-214AB)

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		40	V
$I_{F(RMS)}$	RMS forward current		10	A
$I_{F(AV)}$	Average forward current	$T_c = 120^\circ\text{C} \ \delta = 0.5$	3	A
$I_{FSM}$	Surge non repetitive forward current	$tp = 10 \text{ ms Sinusoidal}$	75	A
$I_{RRM}$	Repetitive peak reverse current	$tp=2 \mu\text{s square } F=1\text{kHz}$	1	A
$T_{stg}$	Storage temperature range		- 65 to + 175	°C
$T_j$	Maximum operating junction temperature *		150	°C
$dV/dt$	Critical rate of rise of reverse voltage		10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j - a)}$  thermal runaway condition for a diode on its own heatsink

## STPS3L40S

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to leads	18	°C/W

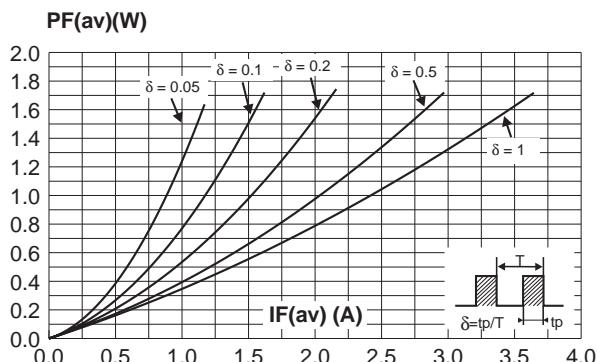
### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Typ.	Max.	Unit
$I_R$ *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$		100	$\mu\text{A}$
		$T_j = 125^\circ\text{C}$		16	40	$\text{mA}$
$V_F$ *	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 3 \text{ A}$		0.5	V
		$T_j = 125^\circ\text{C}$	$I_F = 3 \text{ A}$	0.40	0.44	
		$T_j = 25^\circ\text{C}$	$I_F = 6 \text{ A}$		0.62	
		$T_j = 125^\circ\text{C}$	$I_F = 6 \text{ A}$	0.52	0.58	

Pulse test : \*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

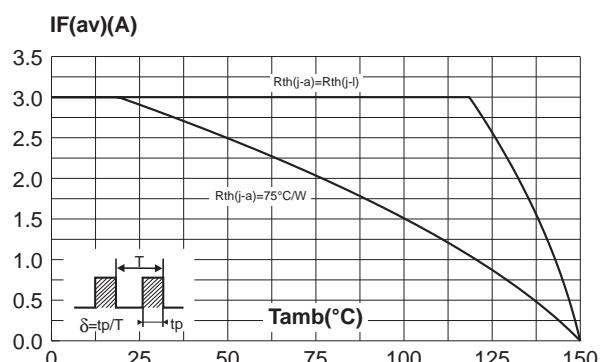
To evaluate the maximum conduction losses use the following equation :  
 $P = 0.30 \times I_{F(AV)} + 0.047 I_F^2(\text{RMS})$

**Fig. 1:** Average forward power dissipation versus average forward current.

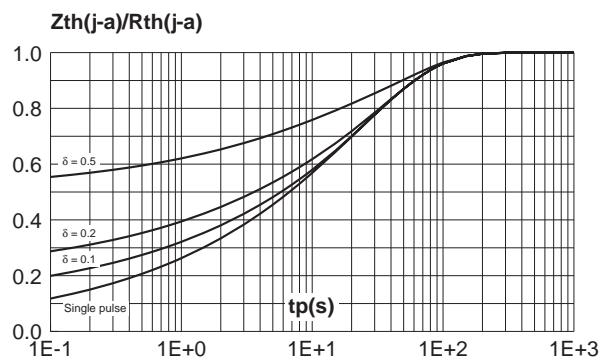
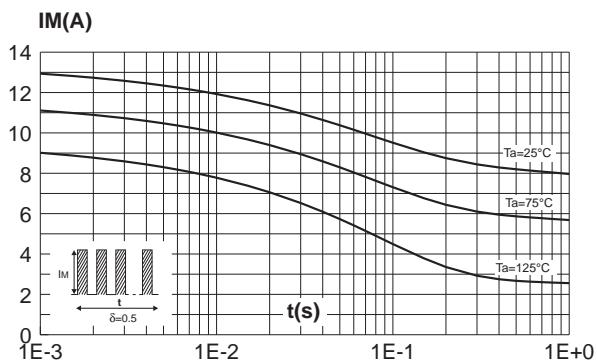


**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values).

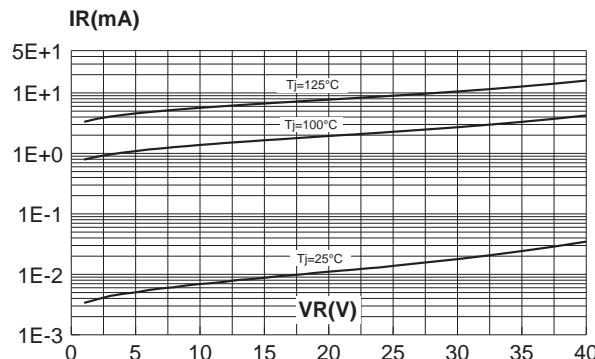
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



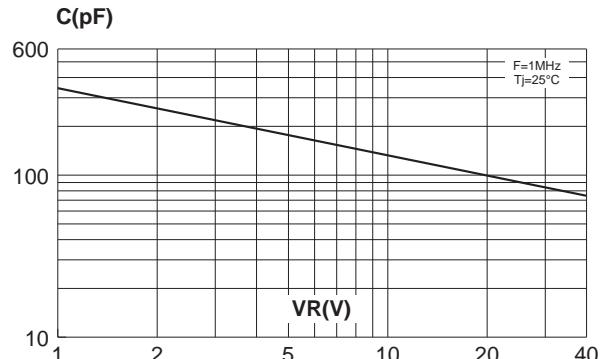
**Fig. 4:** Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board,  $e(\text{Cu})=35\mu\text{m}$ , recommended pad layout).



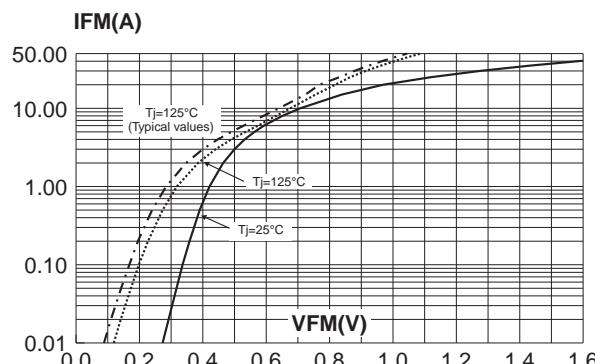
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values).



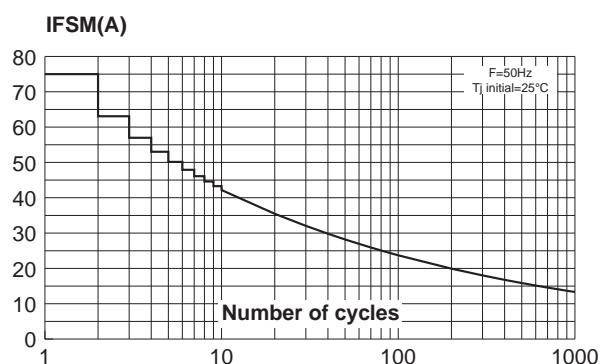
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values).



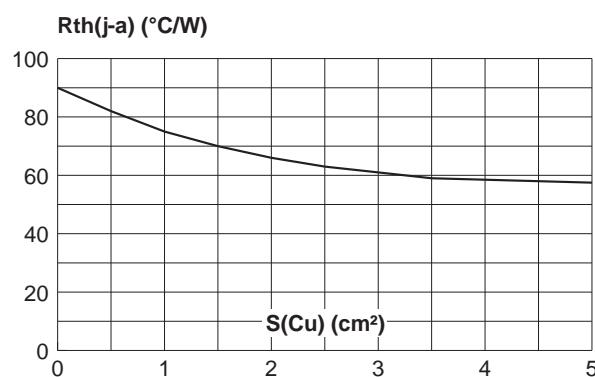
**Fig. 7:** Forward voltage drop versus forward current (maximum values).



**Fig. 8:** Non repetitive surge peak forward current versus number of cycles.



**Fig. 9:** Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35µm).

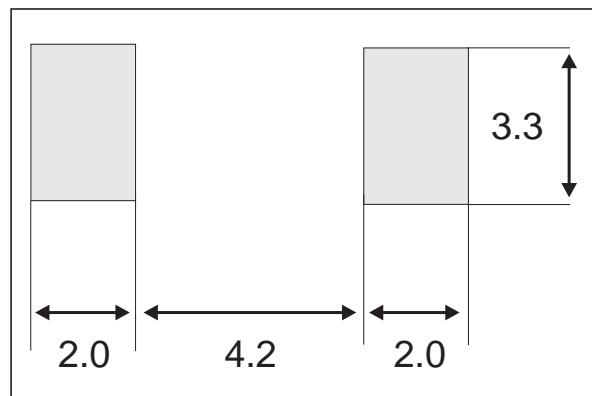


## STPS3L40S

### PACKAGE MECHANICAL DATA SMC

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.60	0.030	0.063

### FOOT PRINT (in millimeters)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS3L40S	S3L4	SMC	0.24g	2500	Tape and reel

- Epoxy meets UL94,V0
- Band indicates cathode

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